

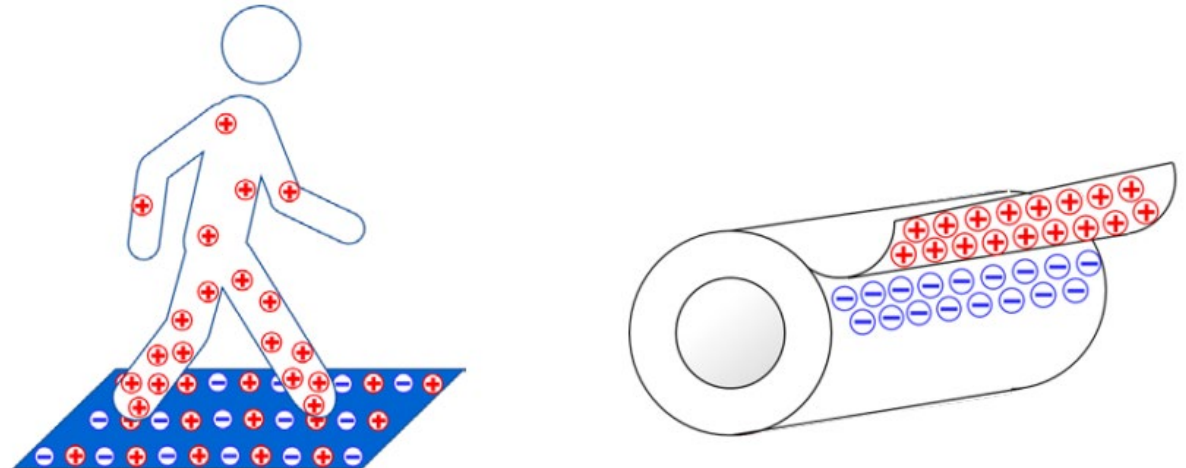
A grayscale microscopic image of a circuit board connection, showing a central solder joint between two conductive traces. A thick white curved line starts from the bottom left and arcs towards the top right, partially overlapping the text on the right side of the image.

# Live Lecture Series #2

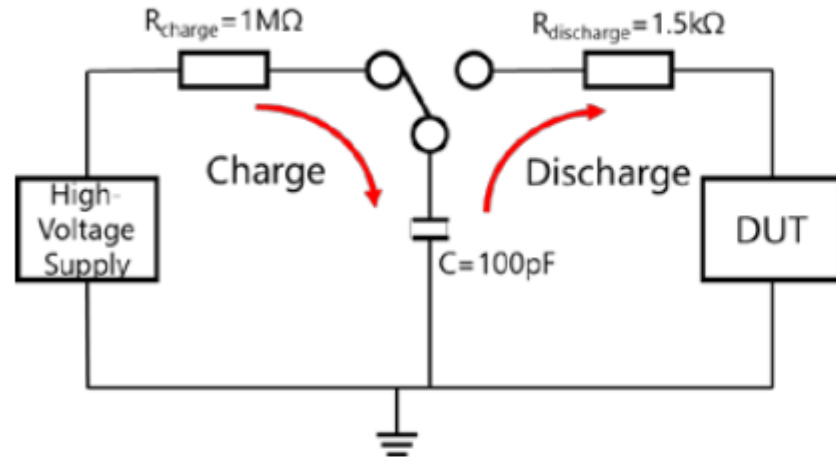
Designing ESD Safe Circuits

# What Exactly Is ESD?

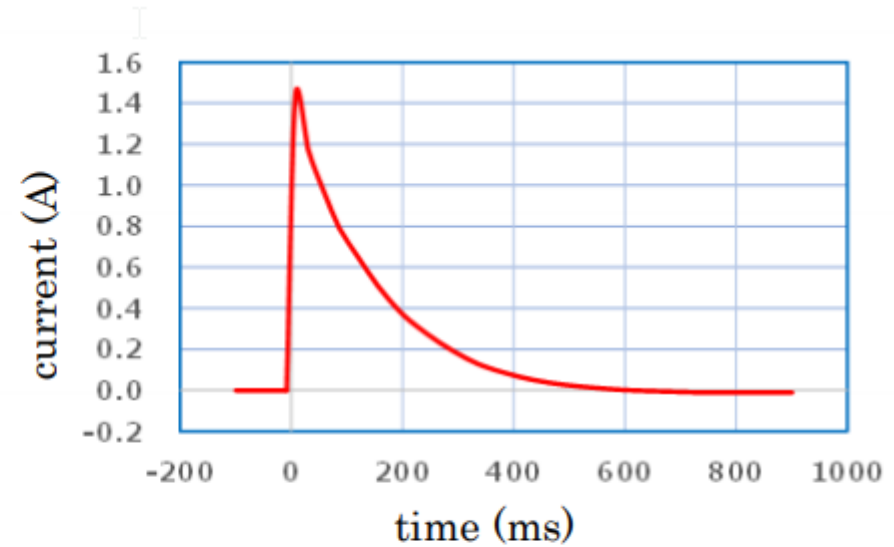
- **ElectroStatic Discharge (ESD)**: is the release of static electricity when two objects come into contact.
- **Device level ESD**: An event that occurs to an unmounted semiconductor in an ESD controlled environment.
- **System level ESD**: An event that occurs to a finished electronic device/widget.



# Device Level Tests



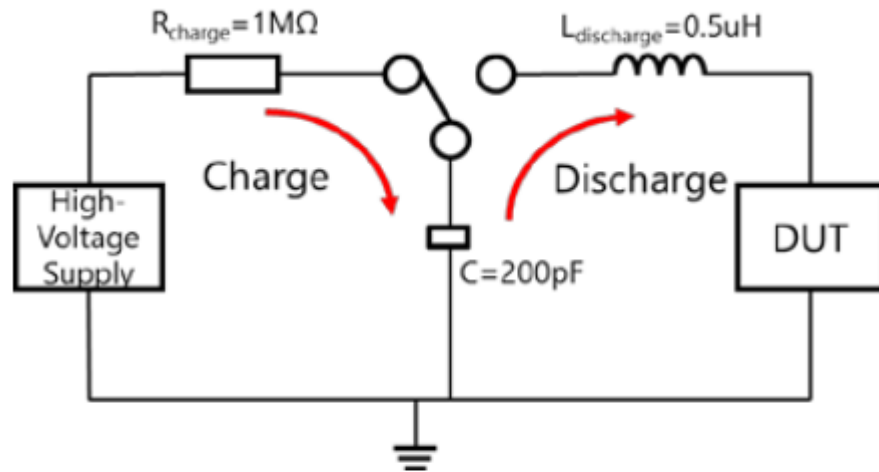
Test circuit example



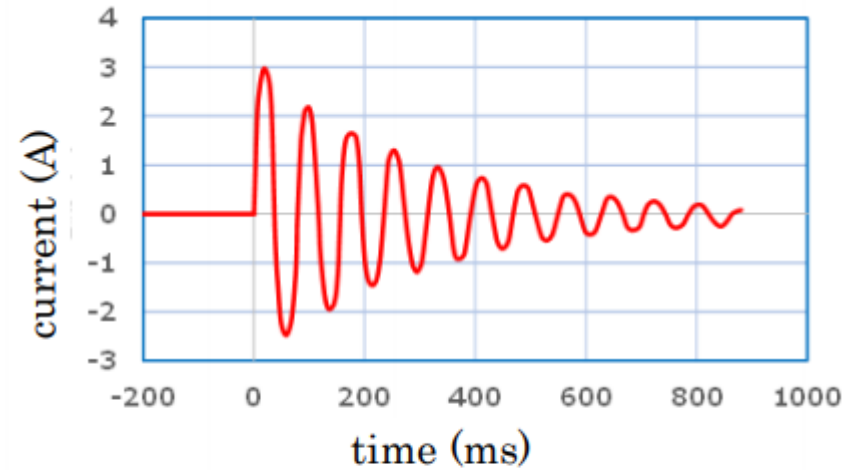
Test waveform example

**Human body model (HBM)**

# Device Level Tests (cont'd)



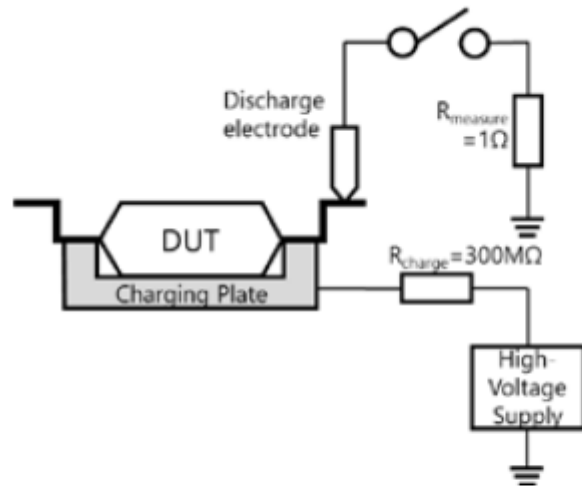
Test circuit example



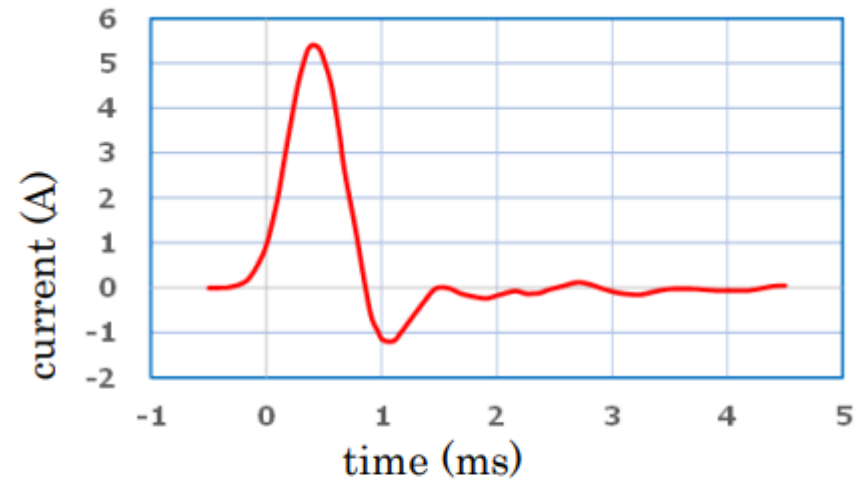
Test waveform example

**Machine model (MM)**

# Device Level Tests (cont'd)



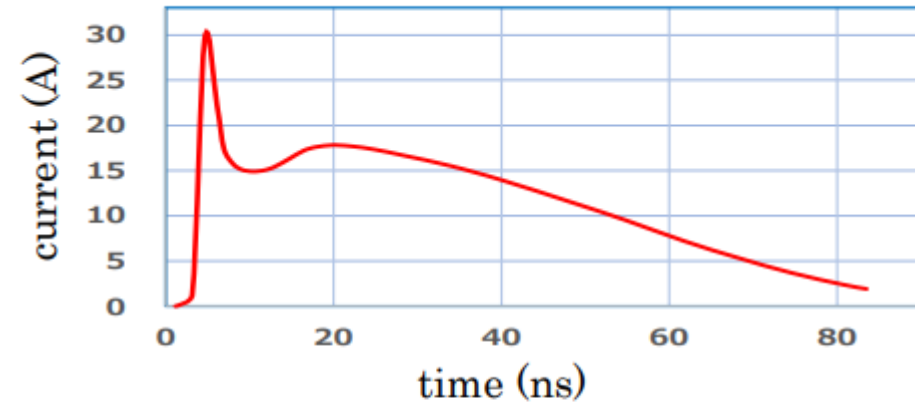
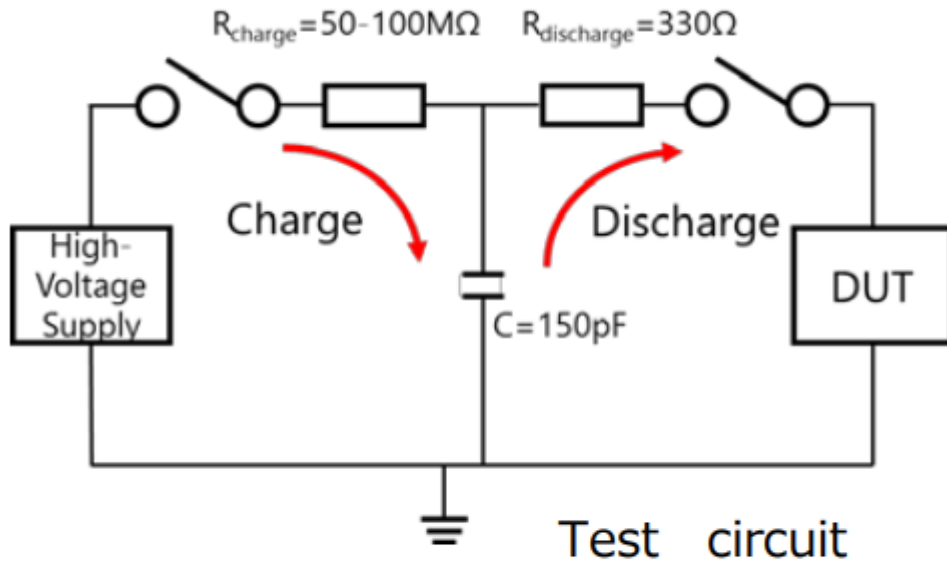
Test circuit example



Test waveform example

**Charged-device model (CDM)**

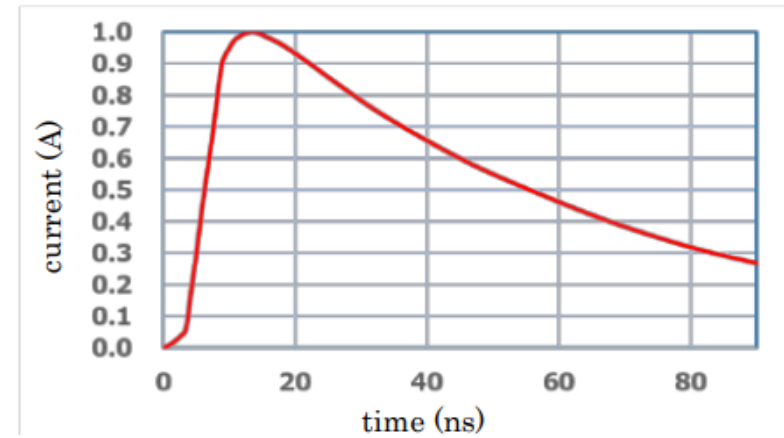
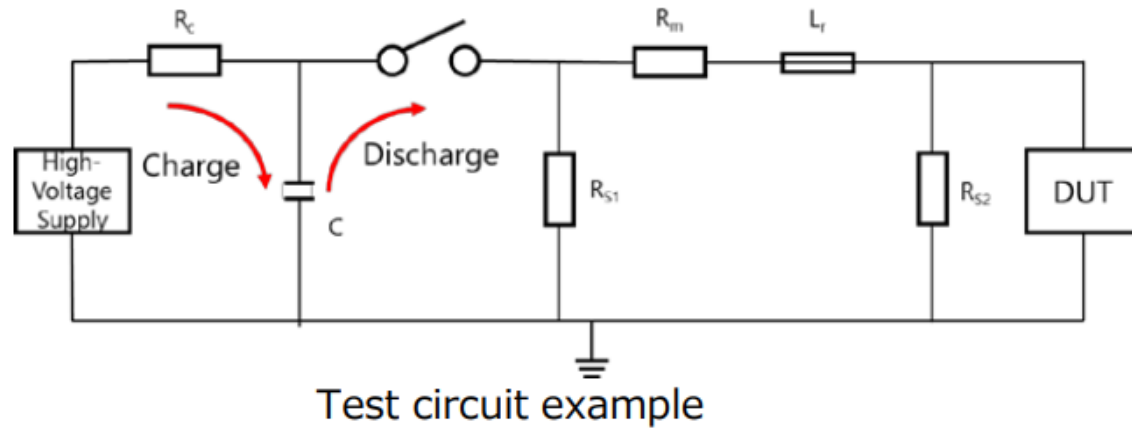
# System Level Tests



Test waveform example

**IEC 61000-4-2 test**

# System Level Tests (cont'd)



Test waveform example

**IEC 61000-4-5 test**

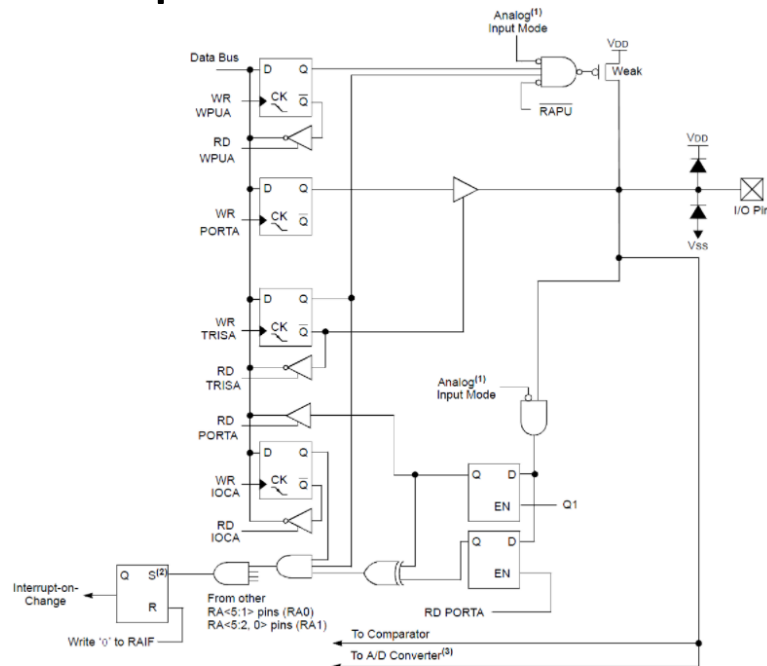
# What Is the Result of a System Level ESD Event?

- No damage at all, system continues as normal
- **Soft Failure**: No physical damage, but the system has a “lockup” or “freeze.” May require physical intervention (i.e., power cycle.)
- **Hard Failure**: Physical damage to the system, may or may not show it immediately (latent defect/failure are the worst).



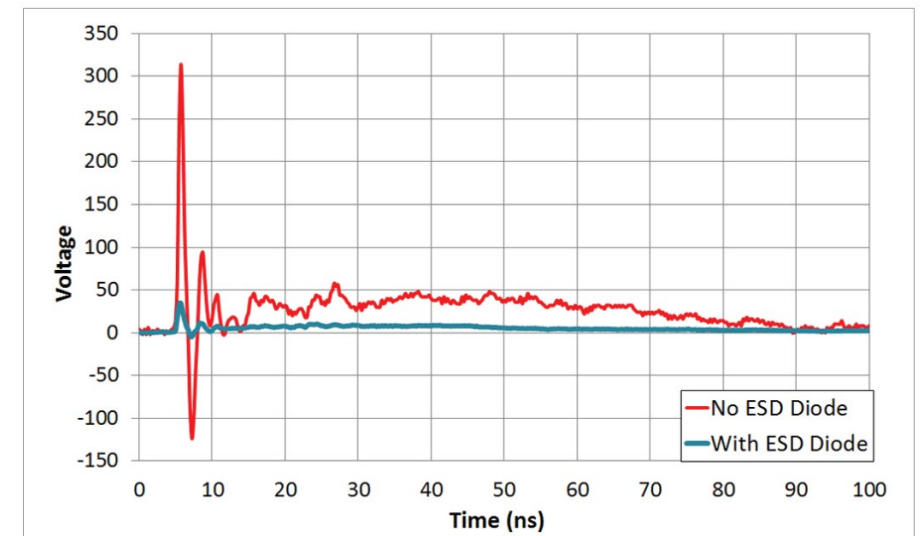
# What is Our Goal With Hardware ESD Protection?

- It is not to try and eliminate all events.
- We want to reduce the event both in voltage and current so the internal IC protection can handle it.



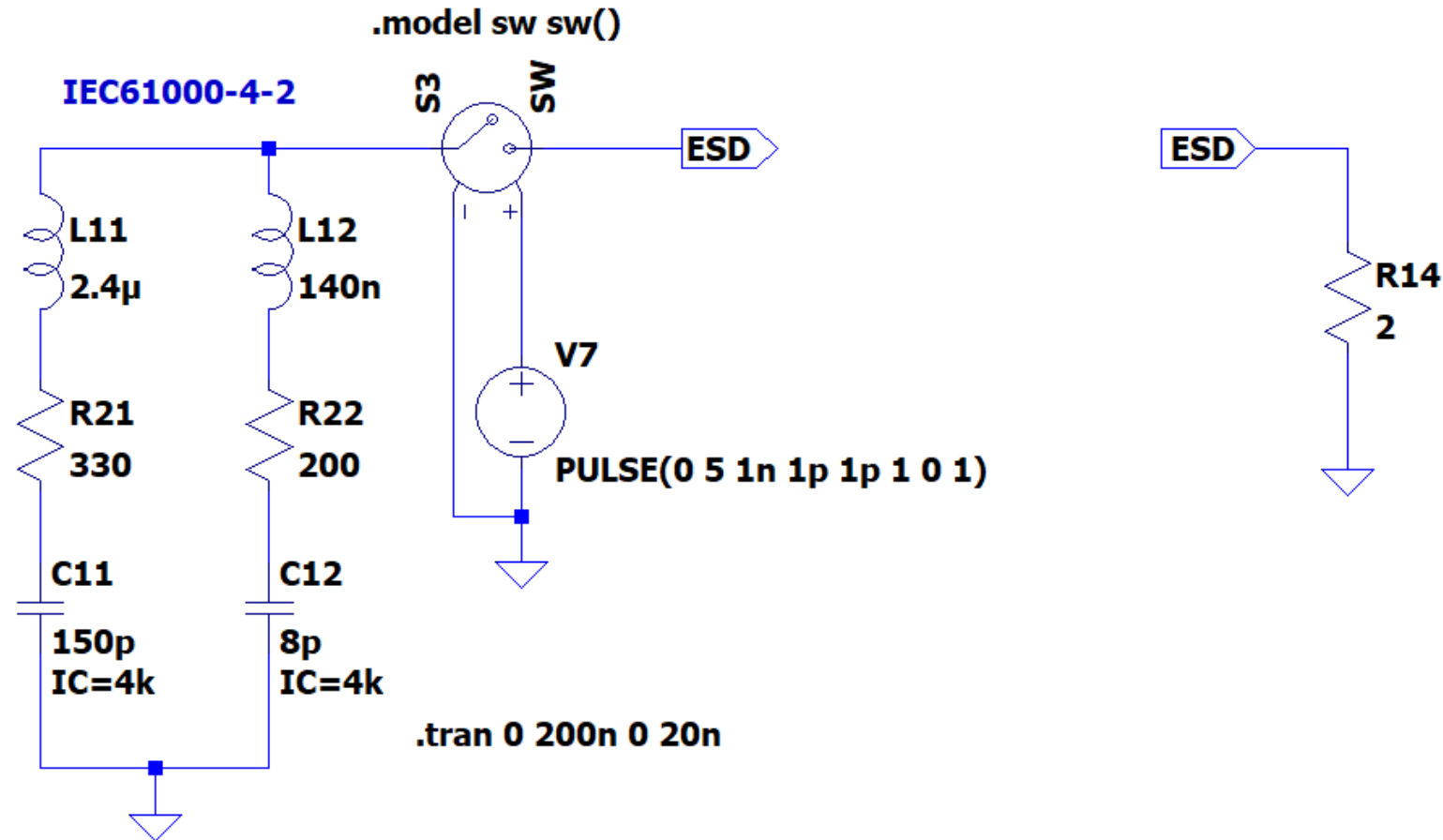
Note 1: Comparator mode and ANSEL determines Analog Input mode.  
2: Set has priority over Reset.  
3: PIC16F616/16HV616 only.

PIC16F616 - Microchip



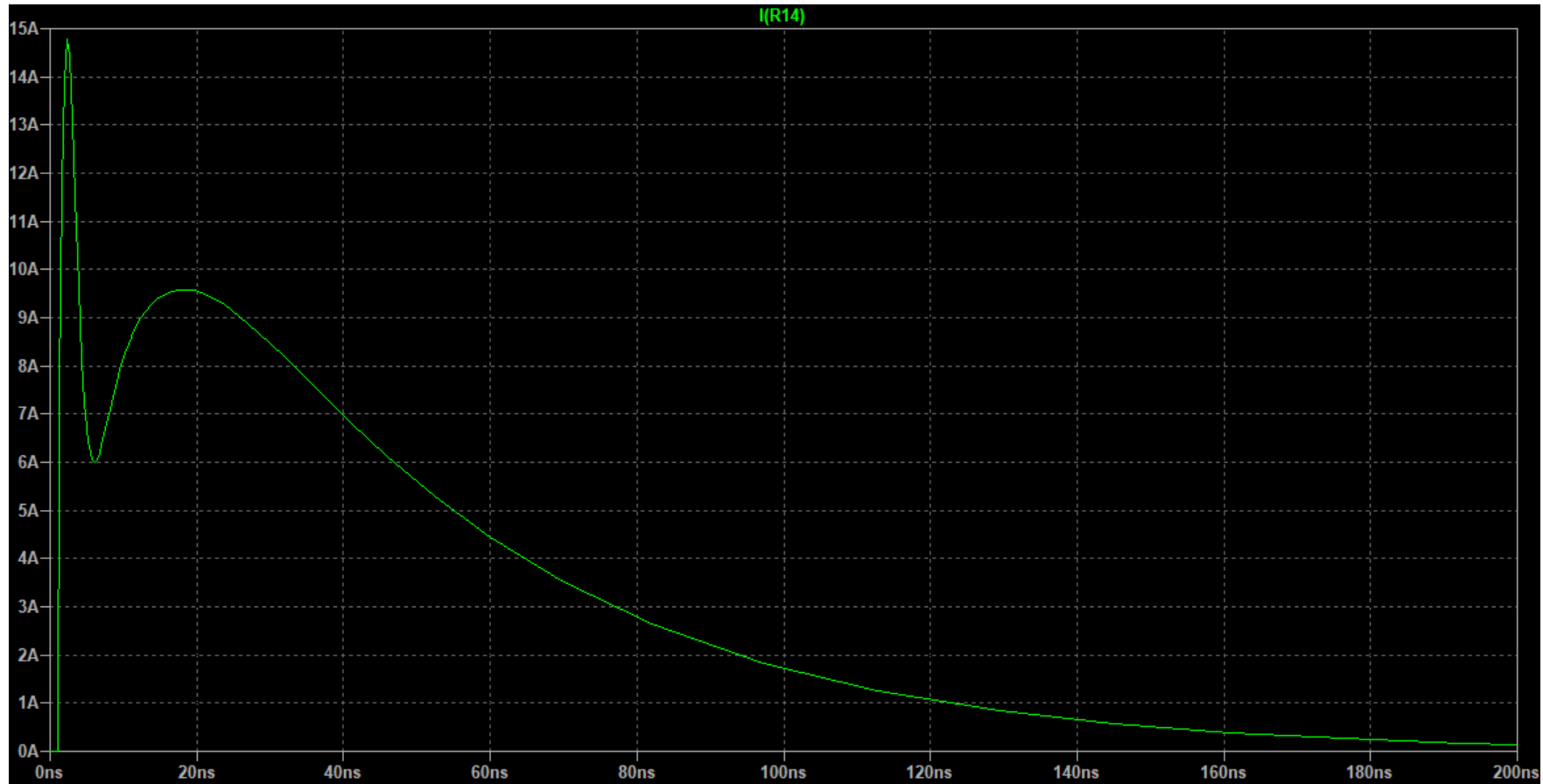
System-Level ESD Protection Guide – Texas Instruments

# LTSpice Simulation IEC61000-4-2



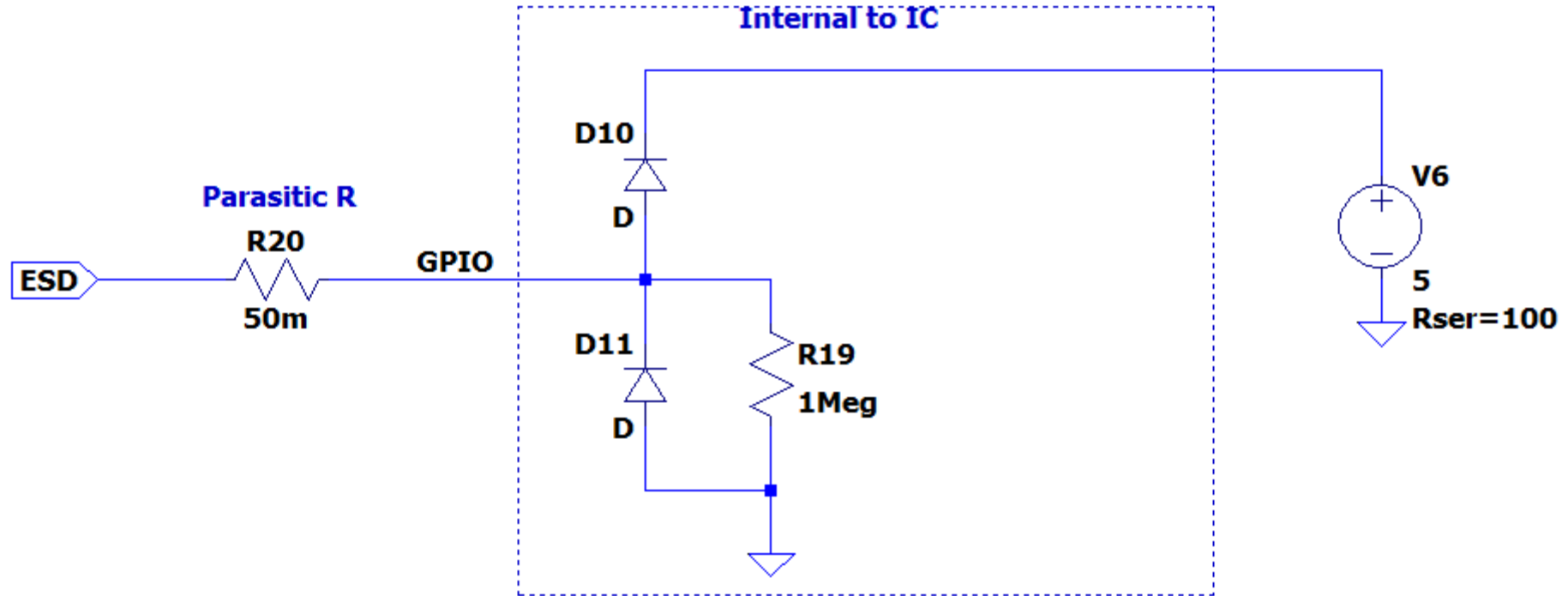
Based off: <https://www.youspice.com/simple-spice-esd-generator-circuit-based-on-iec61000-4-2-standard/>

# LTSpice Simulation: Calibration

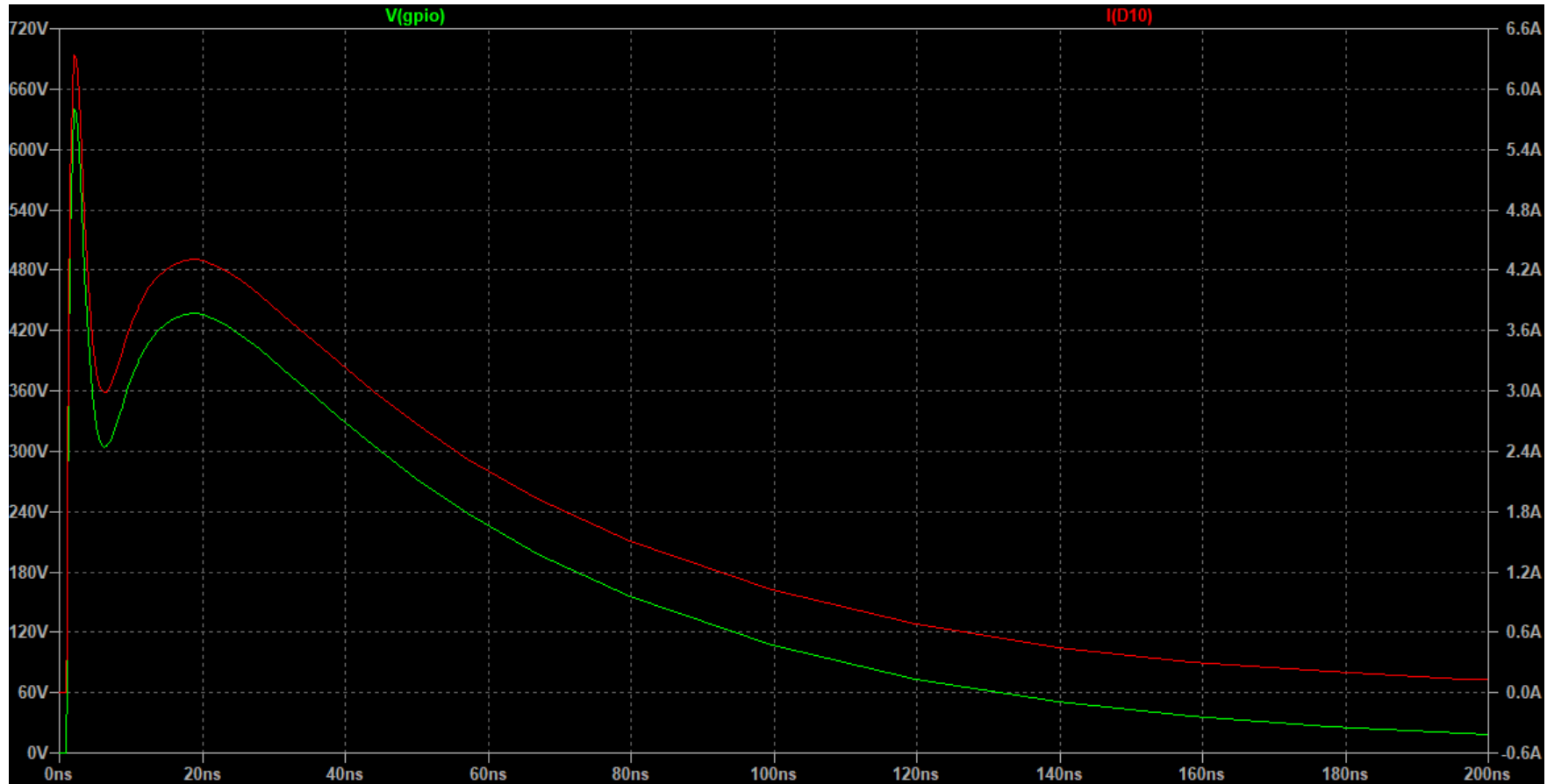


*Using a 2R calibration resistor*

# LTSpice Simulation: No Protection

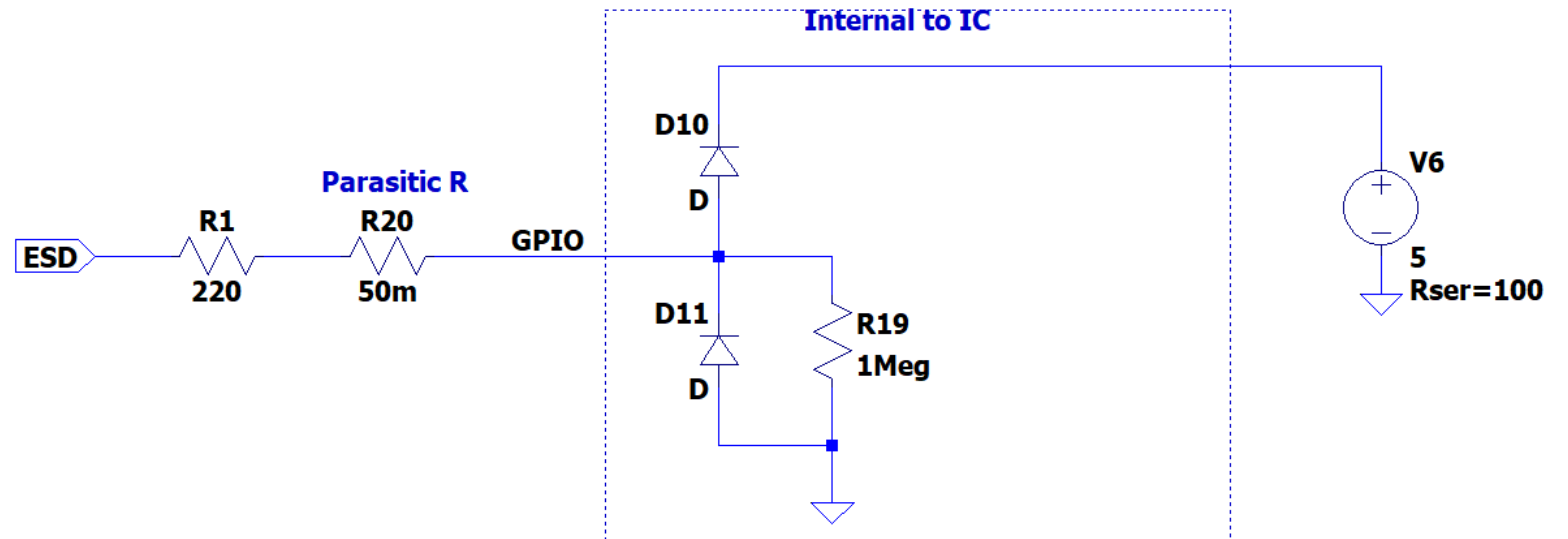


# LTSpice Simulation: No Protection



# Strategy 1: Series Resistors

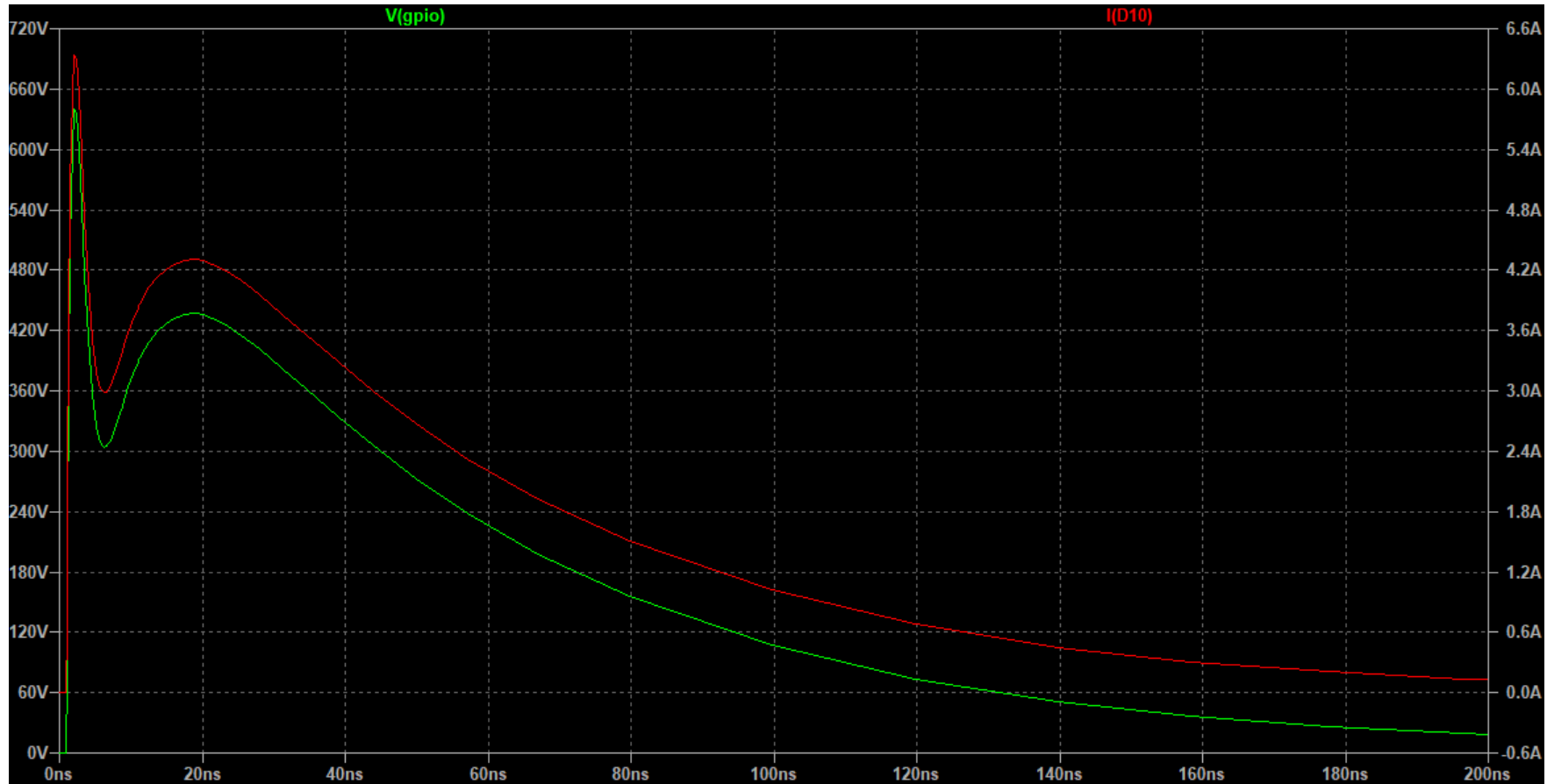
- Limits the peak current.
- Damp ringing.
- Help protect diodes downstream.
- Immensely helpful for general EMC and SI.



# LTSpice Simulation: 220R Series Resistor



# LTSpice Simulation: No Protection

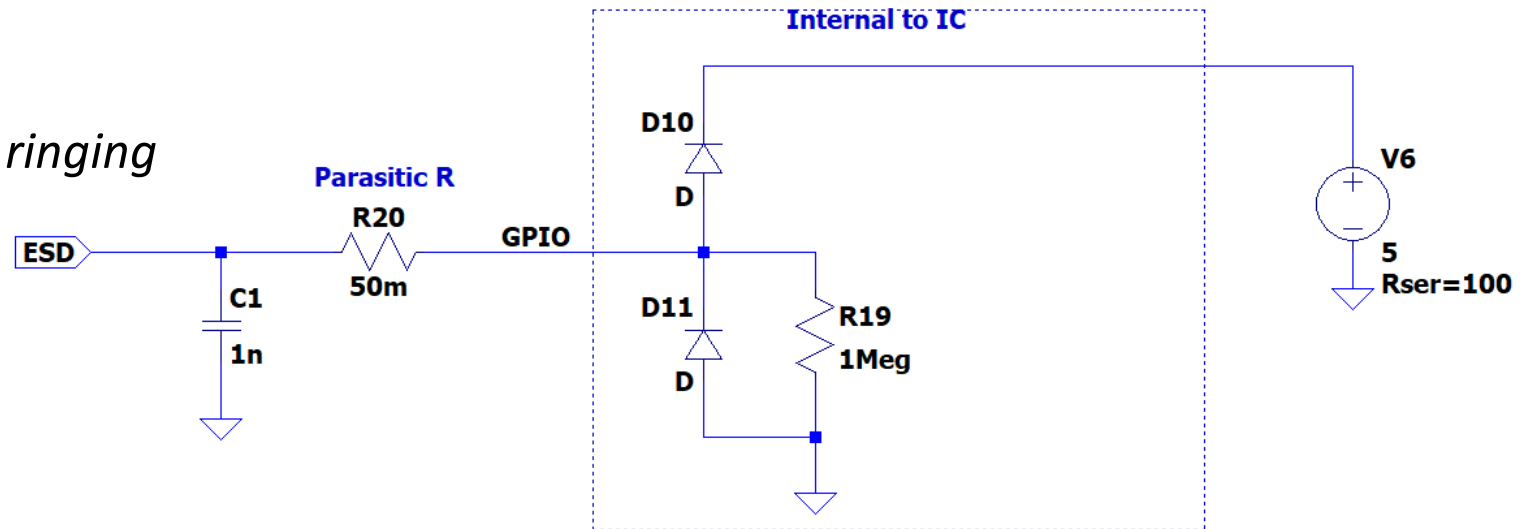




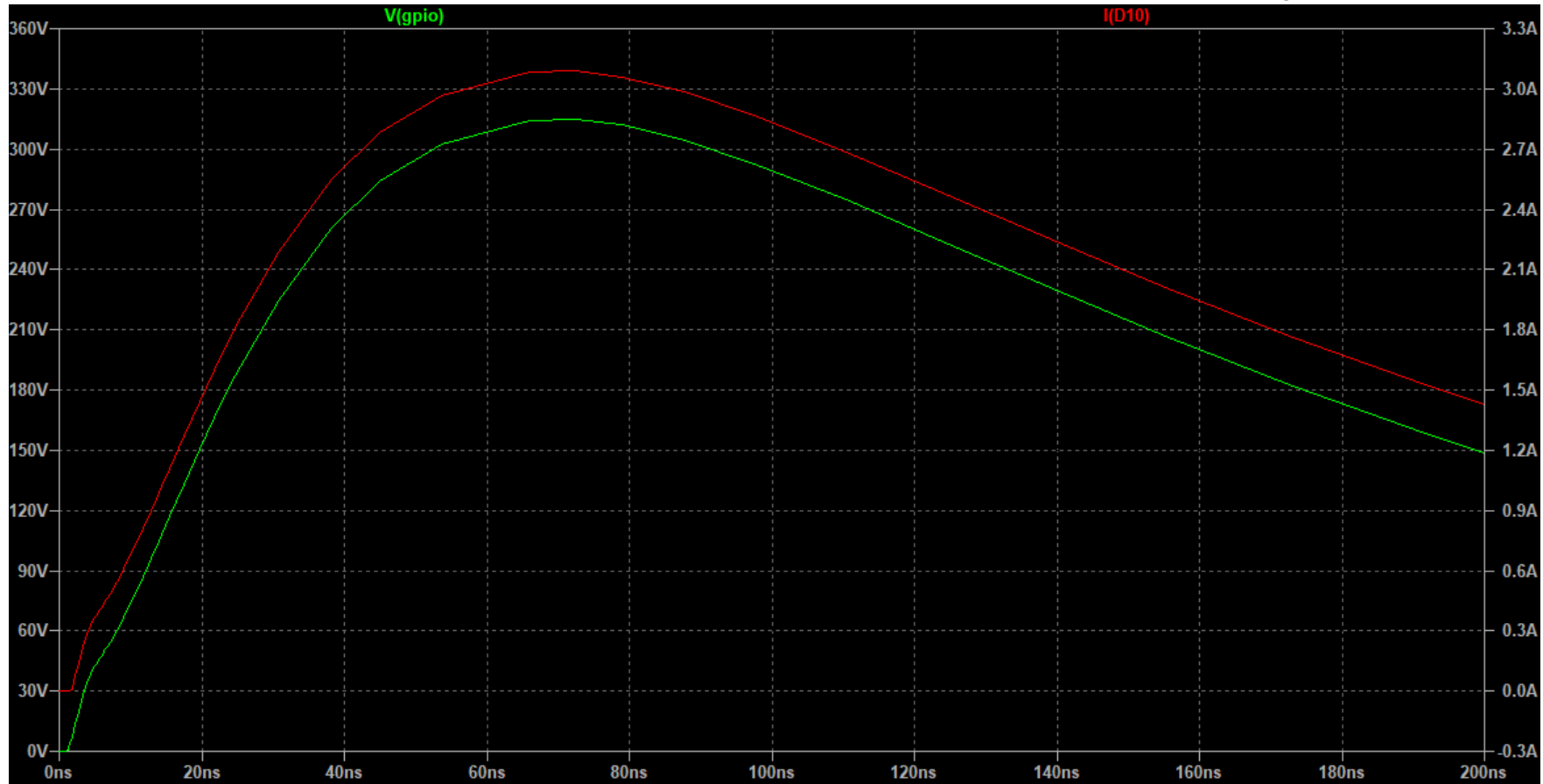
# Strategy 2: Capacitors

- “Soaks up” the voltage spike.
- Smooths out the event.
- Higher the capacitor, the better it will perform\*.
- Can’t use them on high-speed signals.

• *\*If not damped they can introduce ringing*



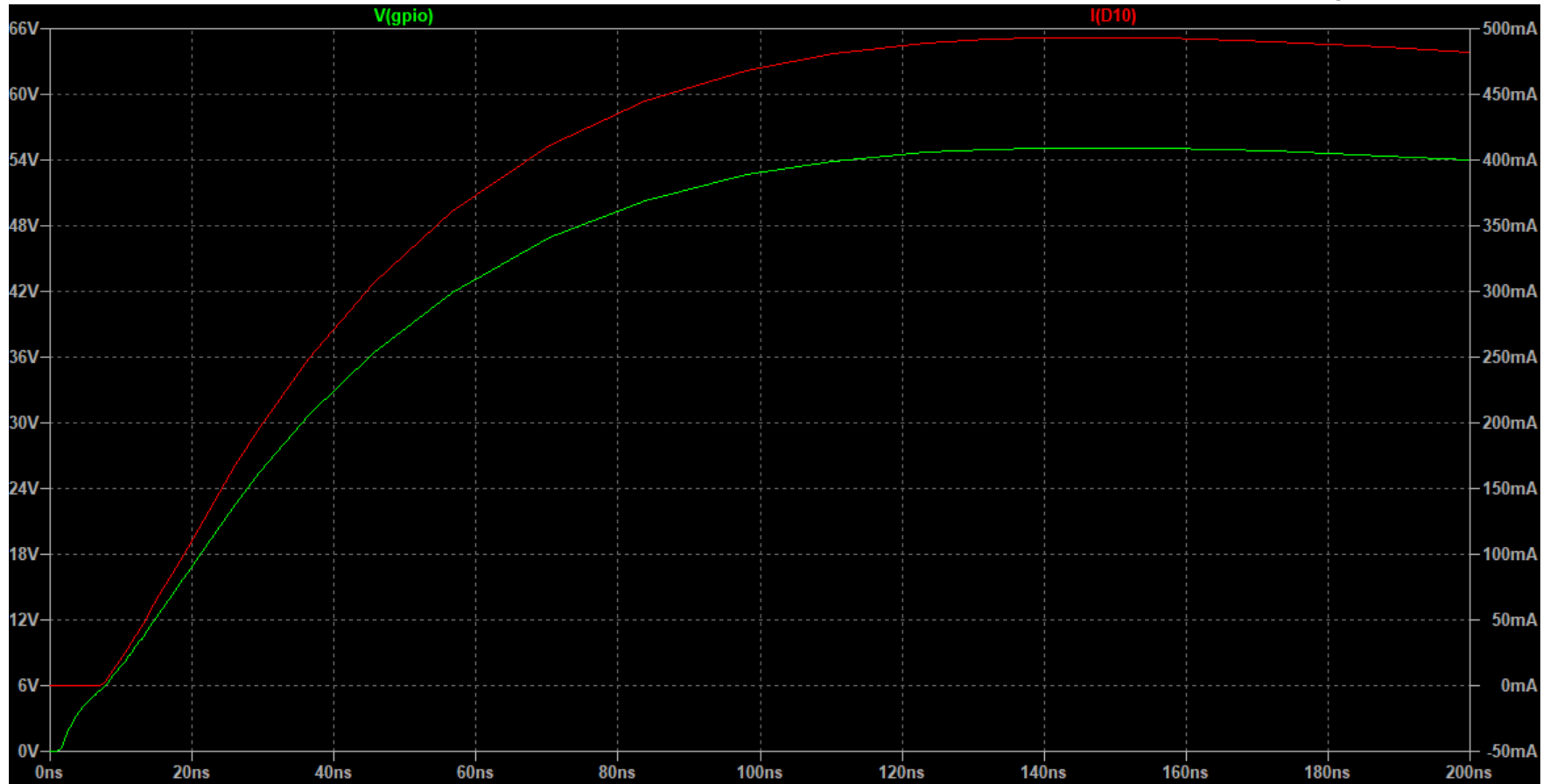
# LTSpice Simulation: 1nF Ceramic Capacitor



# LTSpice Simulation: 220R Series Resistor

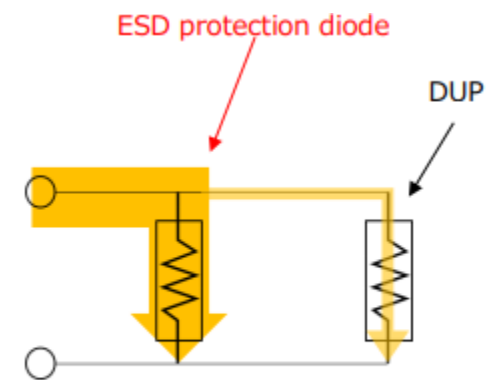


# LTSpice Simulation: 10nF Ceramic Capacitor



# Strategy 3: TVS Diodes

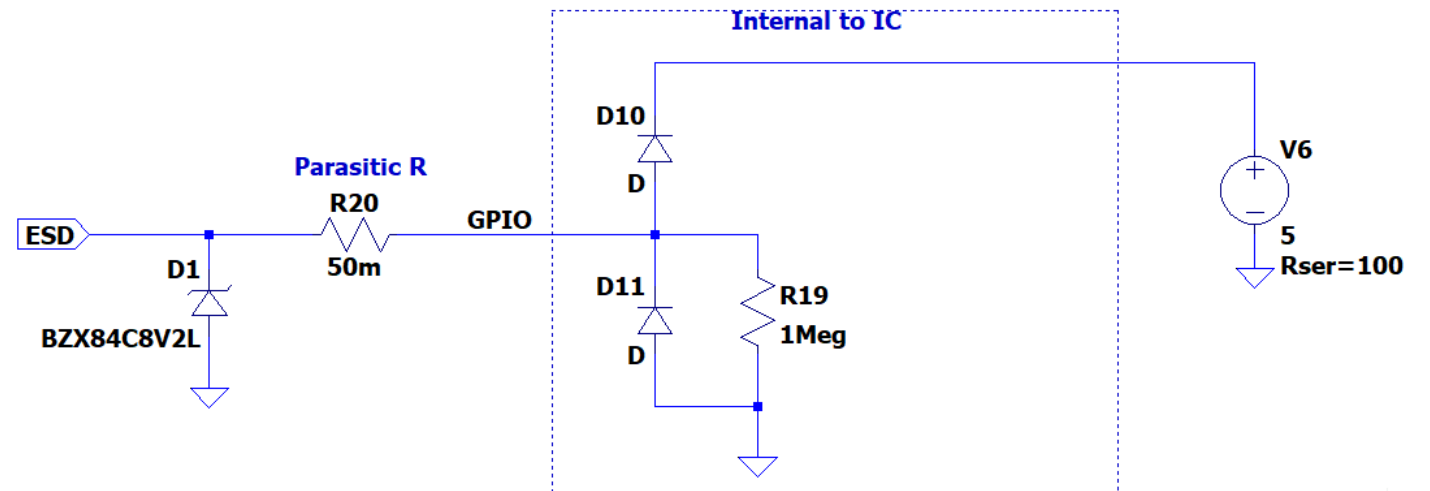
- Essentially act like a Zener diode.
  - *TVS diodes tend to have a faster response and a higher surge current rating.*
- **Reverse Working Maximum Voltage (VRWM)**: The maximum reverse voltage that should be applied in normal operating conditions.
- **Breakdown Voltage (VBR)**: The voltage where the diode just starts to conduct.
- **Clamping Voltage (VCLAMP)**: The maximum voltage that the system will experience during a surge.
- **Dynamic resistance (RDYN)**: The estimated resistance of the diode conducting.



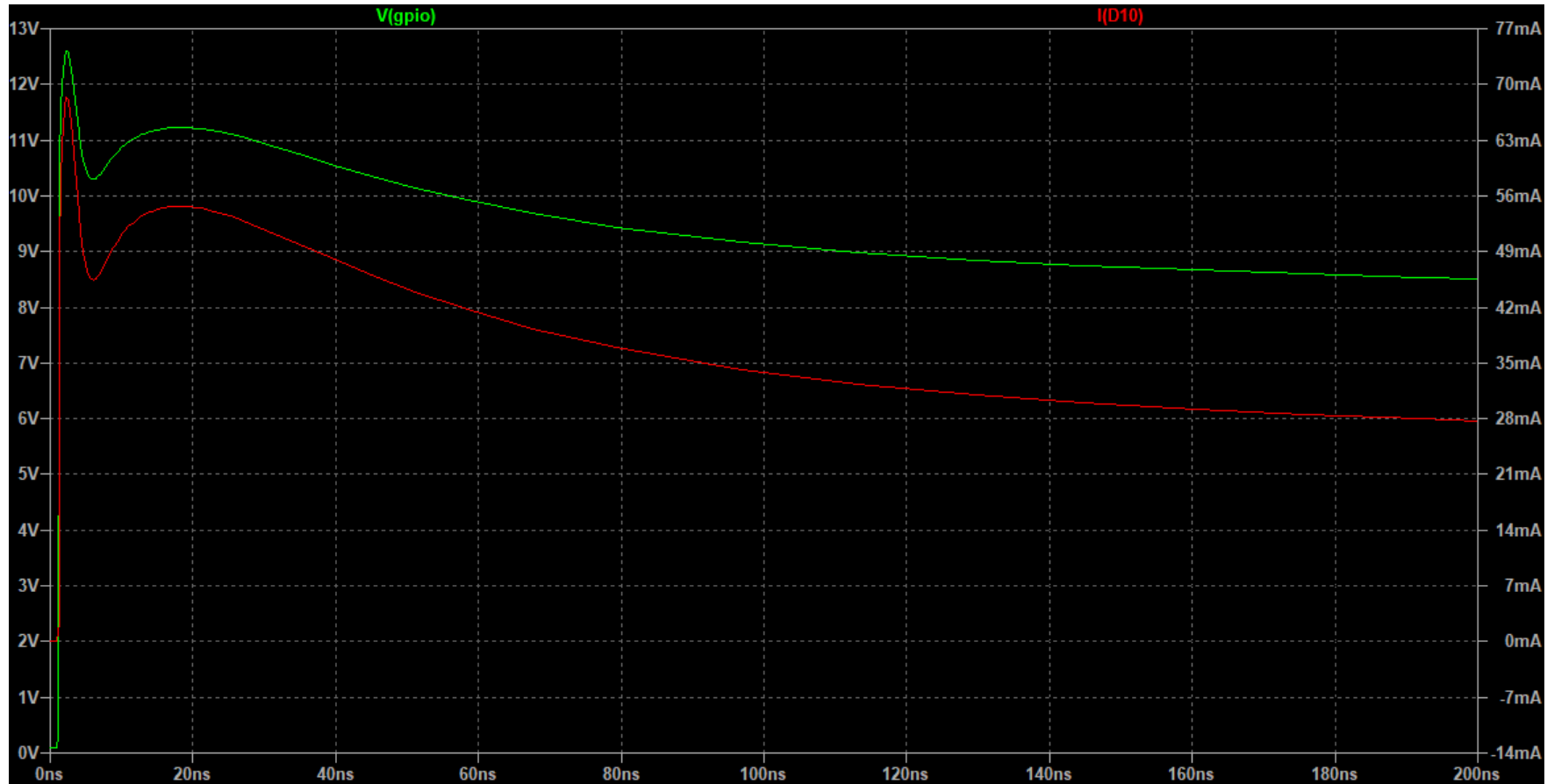
An ESD protection diode with low dynamic resistance helps reduce the amount of current that flows to the DUP.

# Strategy 3: TVS Diodes (Cont'd)

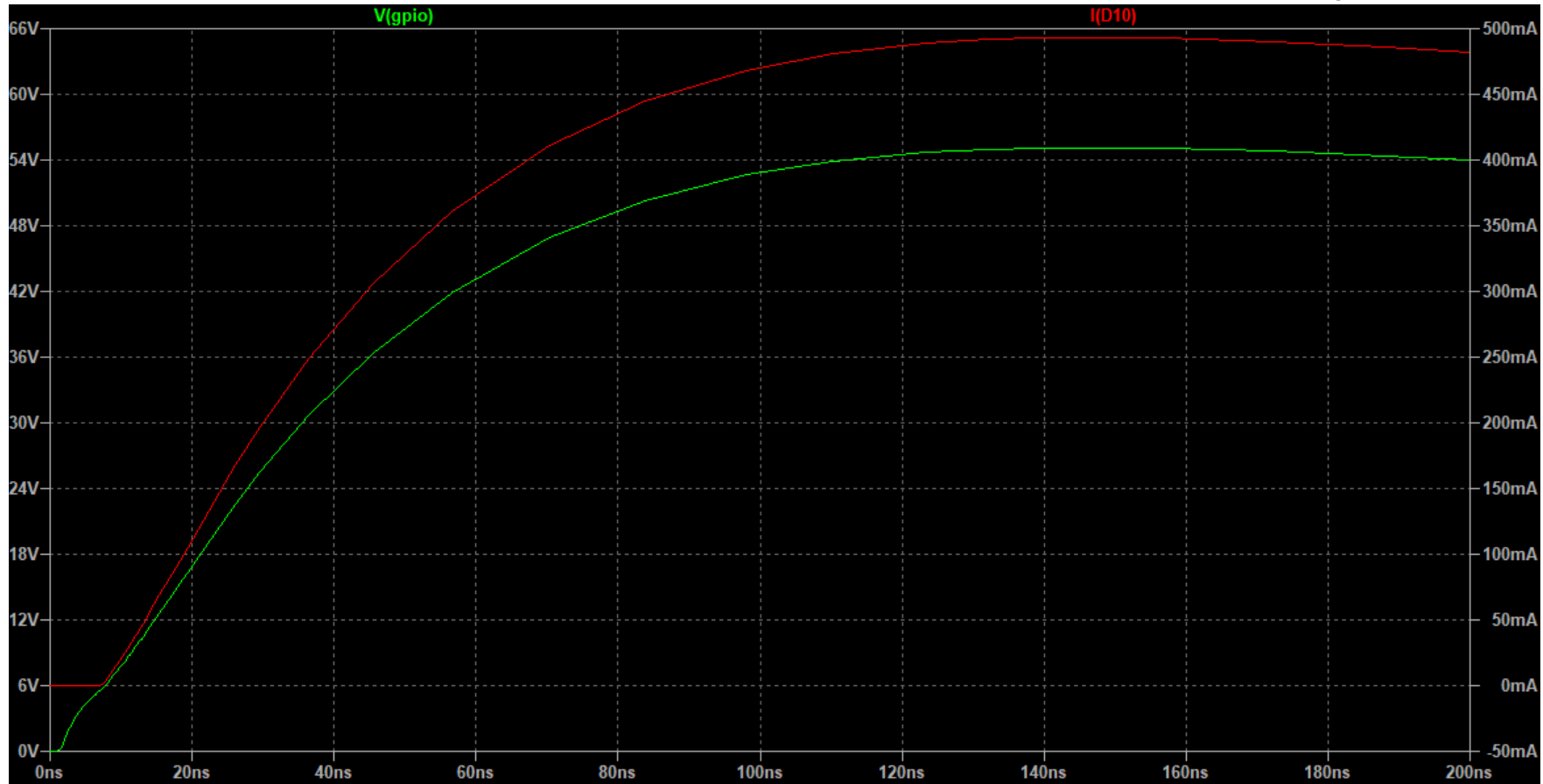
- Unidirectional TVS diodes protect from both positive and negative spikes.
- Bidirectional diodes only are needed for signals that go above and below 0V (RS485)
- TVS capacitance must be lower than the limit of whatever is being protected.



# LTSpice Simulation: 8.2V Zener (TVS)



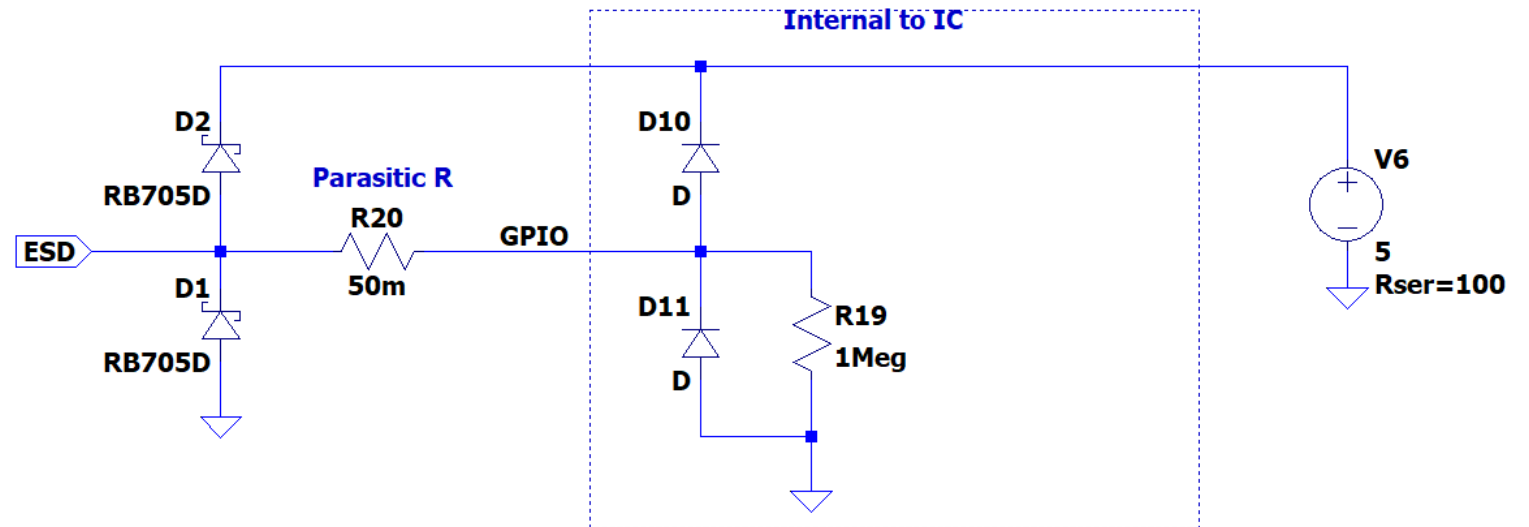
# LTSpice Simulation: 10nF Ceramic Capacitor





# Strategy 4: Dual Schottky Diodes

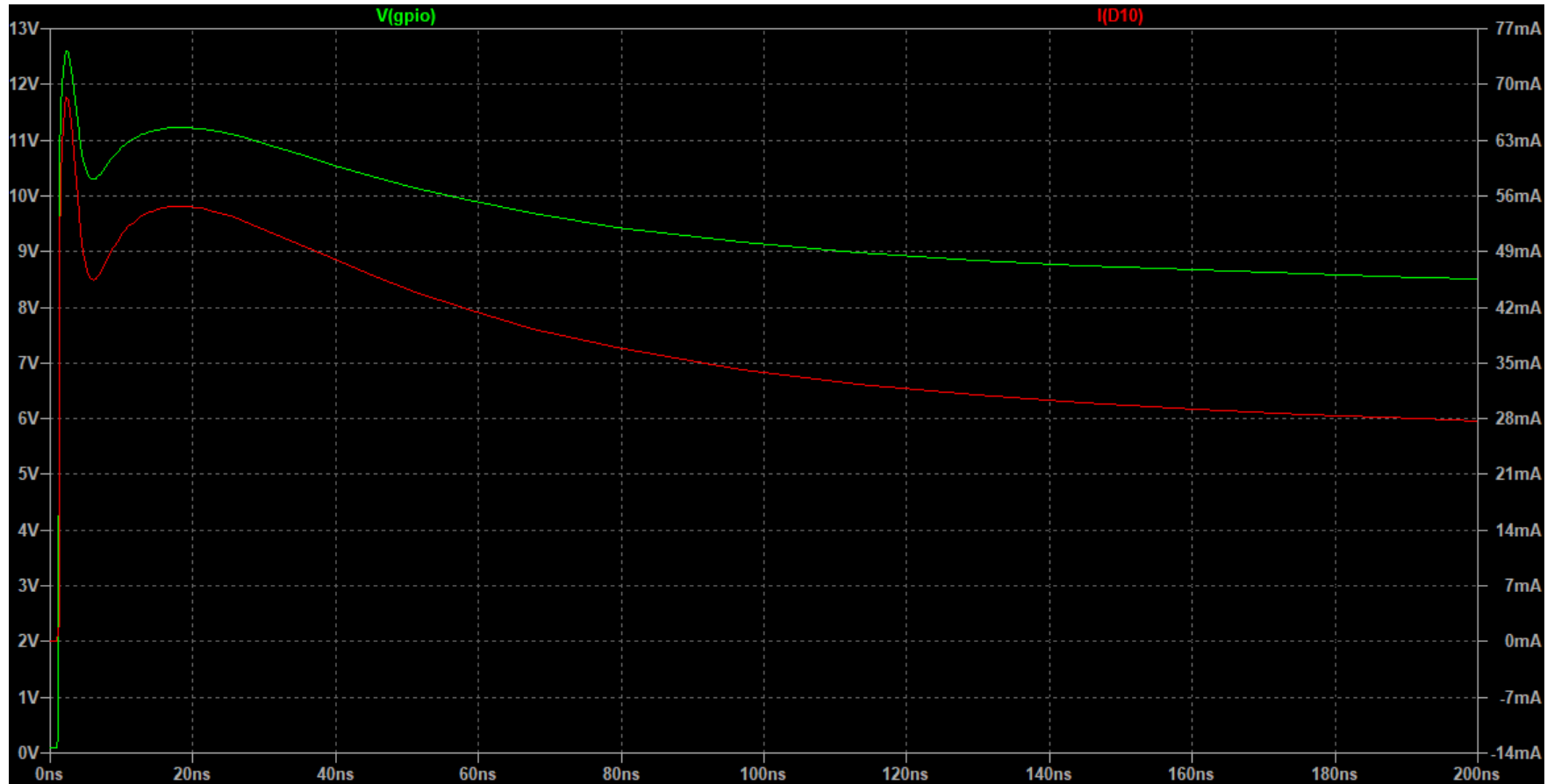
- The goal with dual Schottky's is to have them conduct before the internal diodes.
- This approach is highly dependent on the power rail impedance.
- This approach + series resistors can help limit current and overvoltage to input pins.



# LTSpice Simulation: Dual Schottky Diodes (100R PSU Impedance)



# LTSpice Simulation: 8.2V Zener (TVS)

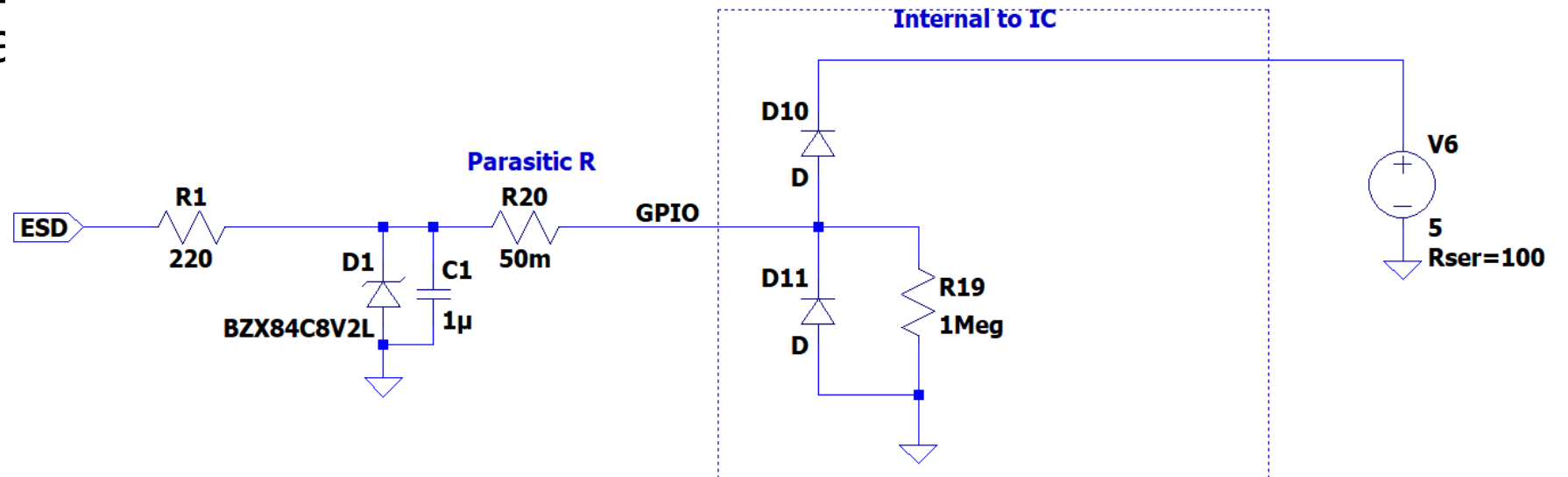


# LTSpice Simulation: Dual Schottky Diodes (10R PSU Impedance)



# What Do I Normally use?

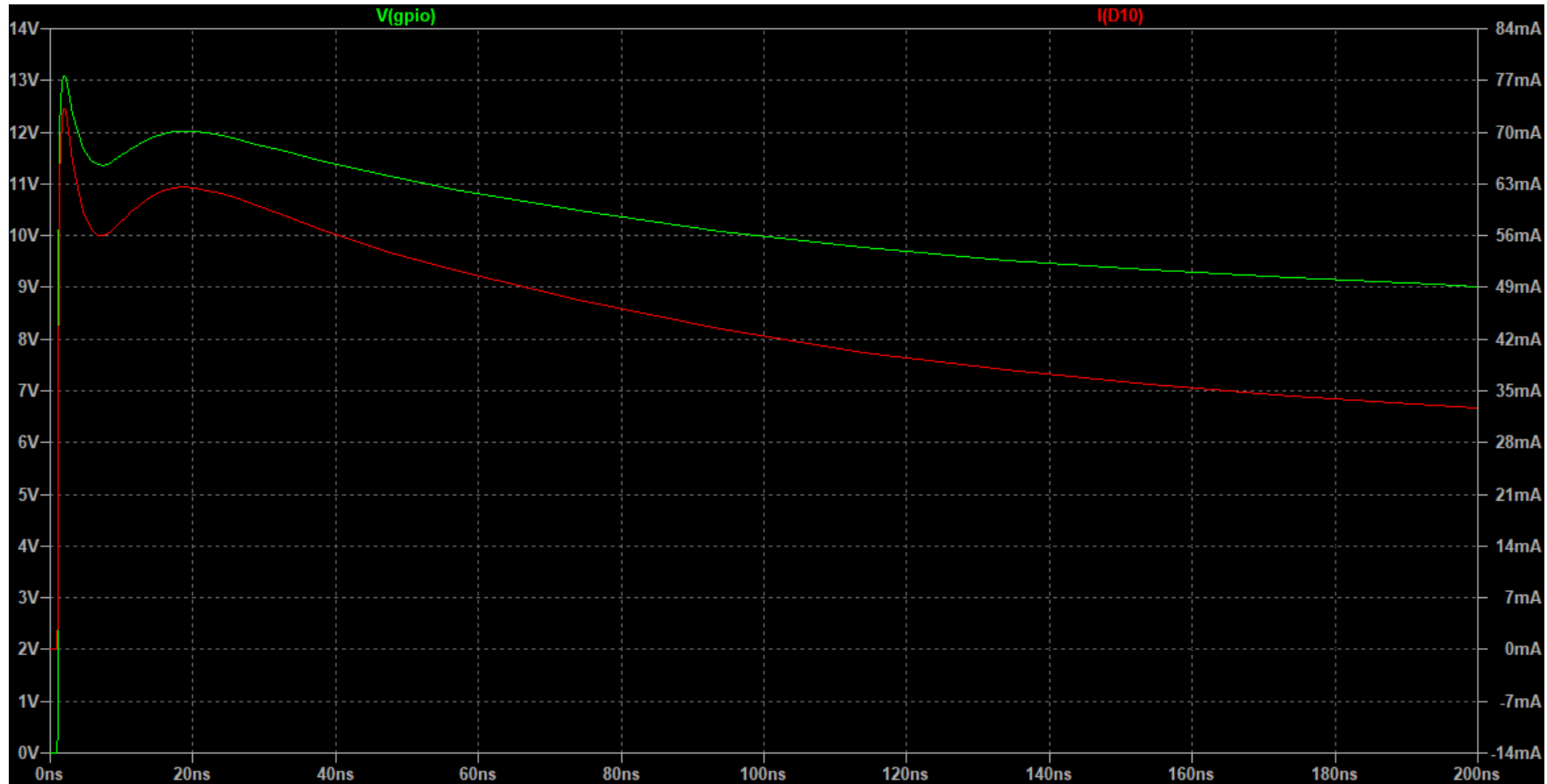
- **High-Speed Interface (USB/Ethernet/HDMI/Etc.):** A single TVS diode rated for that interface.
- **Slow Interface, General Protection:** Same as above, but will add a series resistor before the TVS.
- **Slow Interface Higher Protection:** Same as above but will add a capacitor in parallel



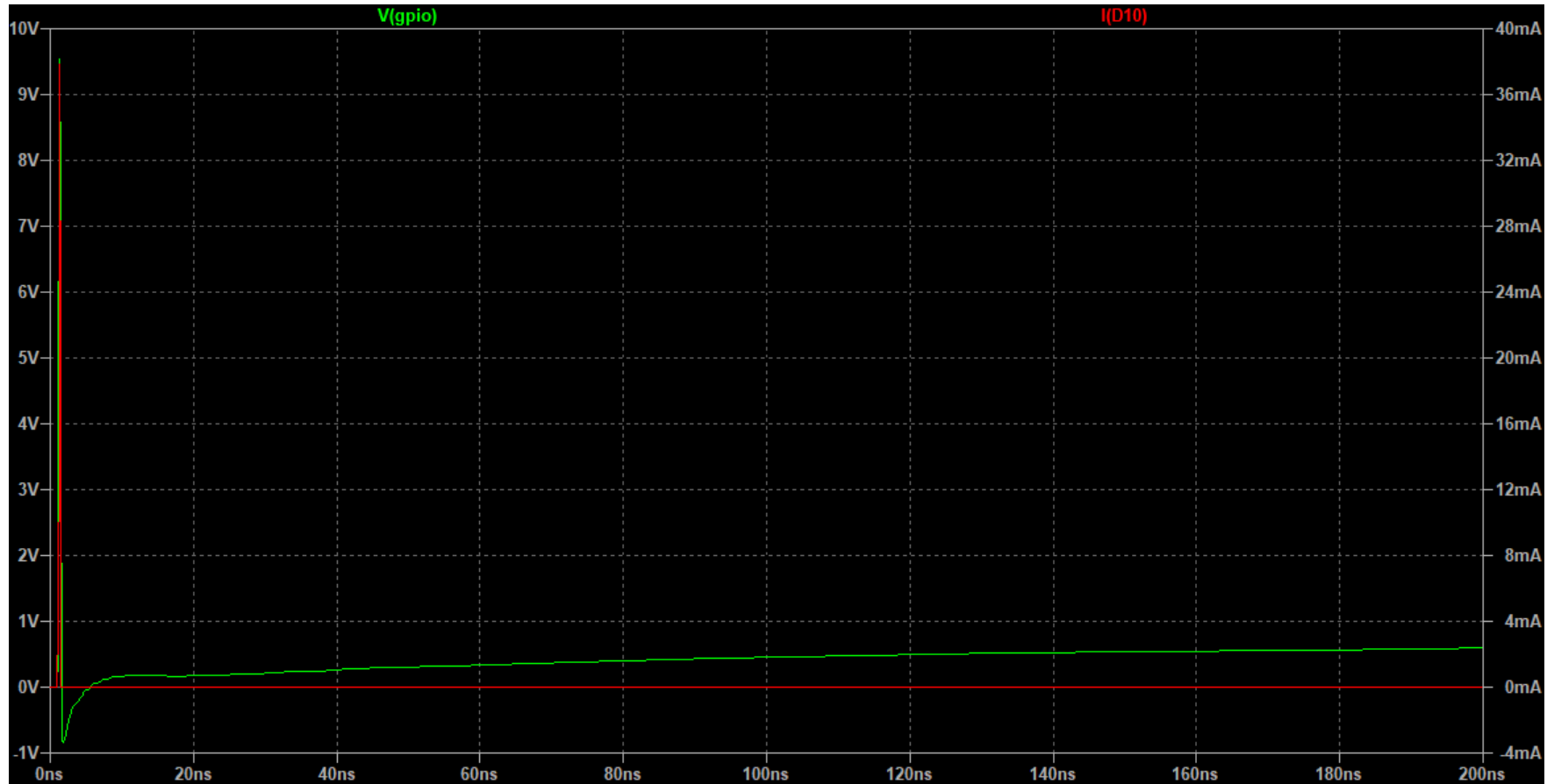
# LTSpice Simulation: 8.2V Zener (TVS)



# LTSpice Simulation: 8.2V Zener (TVS) + 220R



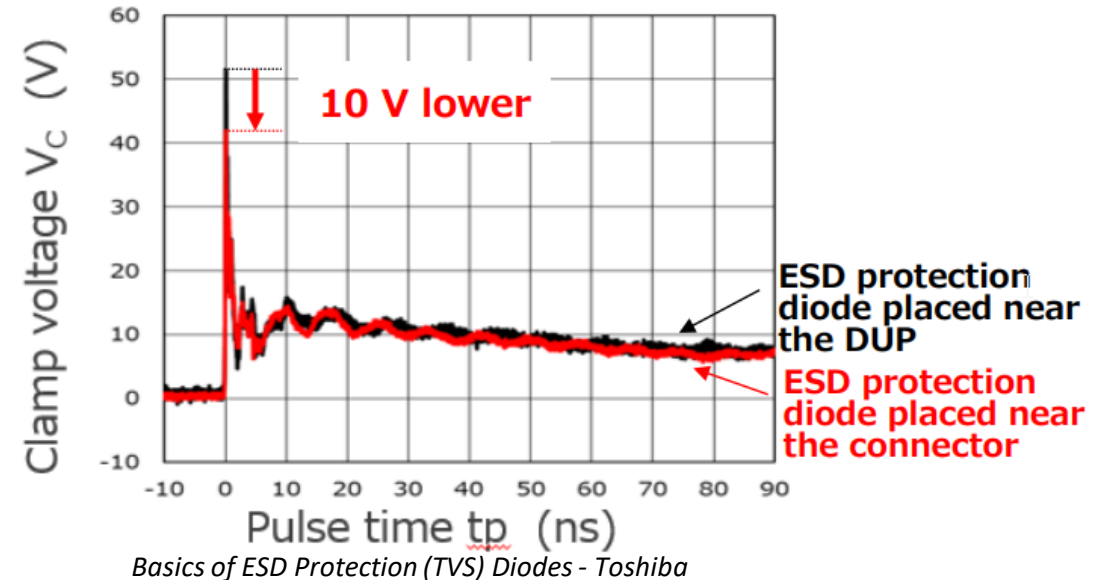
# LTSpice Simulation: 8.2V Zener (TVS) + 220R + 1uF





# PCB Layout considerations

- Protection needs to be as close to the connector/whatever as possible.
  - Low inductance traces.
- Don't run protected traces near unprotected ones.
- Larger the ground plane, the better ( $\epsilon$ )



# Soft Failure Protection

- Primarily relates to firmware/software solutions.
- External watchdog monitor.
- CRC on all communication busses.
- Bit flip detection to force reset (RAM only).

# Conclusion

- There is nearly an unlimited ways to protect a circuit.
- I showed 4 of the common ways that I do it
- It's all about balancing cost/performance.
- When in doubt, use a TVS diode. If the signal is slow and you need additional protection, add in a series resistor or parallel capacitor.
- The software/firmware side can't be ignored.